



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

23-JUL-2004

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #13554

TITLE: Qualification of XFAB-Texas Wafer Fab for Additional Devices

EFFECTIVE DATE: 23-Nov-2004

AFFECTED CHANGE CATEGORY: Subcontractor Fab Site

AFFECTED PRODUCT DIVISION: Analog Products

ADDITIONAL RELIABILITY DATA: None

SAMPLES: No

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Karen Oppen <FFBXP@onsemi.com >

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCEN) –

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

XFAB located in Lubbock, Texas will be qualified as a second source fab for the devices listed below, in addition to the devices previously referenced in PCN #13840. This continued capacity expansion will support customers via an assured supply from ON Semi. The current devices include the NCP1501, NCP2890, NCP1510, NCP4894, and NCP4896. XFAB-Lubbock is currently qualified by ON Semiconductor and is ISO-9001/9002, MIL_PRF_38535, QS-9000, VDA 6.1, and ISO TS 16949 certified.

**Initial Product/Process Change Notification #13554****QUALIFICATION PLAN:**

XFAB-Lubbock is currently qualified for other ON Semi devices. Device performance will not change. For leaded packages (Micro8), characterization, ESD and Latch-up testing will be completed and verified against data from the existing manufacturing site, XFAB located Erfurt, Germany. For devices in the micro-bump package, Temperature Cycling, -40C to 125C for 500 cycles, will be added. Data will be available upon request.

AFFECTED DEVICE LIST (WITHOUT SPECIALS):**PART**

NCP1501DMR2
NCP1501DMR2G
NCP1510FCT1G
NCP2890DMR2
NCP2890DMR2G
NCP4894FCT1
NCP4894FCT1G
NCP4896FCT1G